Preliminary Amendment

Applicant:

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Title:

COOLING SYSTEM FOR DEVICES HAVING POWER SEMICONDUCTORS AND METHOD

FOR COOLING THE DEVICE (as amended)

IN THE ABSTRACT

Please replace the Abstract with the following rewritten paragraph:

COOLING SYSTEM FOR DEVICES COMPRISING HAVING POWER SEMICONDUCTORS AND METHOD FOR COOLING SAID TYPE OF THE DEVICE

The invention relates to a A cooling system (22) for devices eemprising having power semiconductors (1) and a method for cooling said type of the device is disclosed. For this purpose In one embodiment, the cooling system has printed circuit boards (4) arranged on a circuit carrier (10) in plug-in contact strips (7). The cooling system itself has a cooling plate (11), which is mounted in a pivotable manner on one of the plug-in contact strips (7) in the region of the power semiconductor component (1). The cooling plate (11) can be pivoted about an axis (14) in such a way that it assumes a first position, which is pivoted away from the printed circuit board (4), and a second position, in which the cooling plate (11) bears on the power semiconductor component (1).

Figure 1